



SUGGESTED PCB LAYOUT
(COMPONENT SIDE)

- MATERIALS:
HOUSING: HIGH TEMP. THERMOPLASTIC, BLACK, UL 94V-0
CONTACTS: 0.014 INCHES (0.35 MILLIMETERS) THICK PHOSPHOR BRONZE PLATED WITH 150 MICRONS (3.81 MICROMETERS) MINIMUM THICK TIN LEAD IN SOLDER AREA.
15 MICRONS (0.38 MICROMETERS) MINIMUM GOLD IN LOCALIZED PLATE AREA.
ENTIRE CONTACTS PLATED WITH 50 MICRONS (1.27 MICROMETERS) MINIMUM THICK NICKEL.
SHIELDED: 0.0098 INCHES (0.25 MILLIMETERS) THICK COPPER ZINC ALLOY PLATED WITH 30 MICRONS (0.762 MICROMETERS) MINIMUM THICK NICKEL
- JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F
- PART NUMBER: XRJM-S-08-8-8-X
REFER TO LED OPTIONS TABLE FOR ORDERING CODES

NOTES: UNLESS OTHERWISE SPECIFIED
UNSPECIFIED TOLERANCE: .XX±0.010[0.25]
.X±0.006[0.15]

PCB LAYOUT
TOLERANCE
.XX±0.05[0.002]

XMULTIPLE		CONNECTING THE INFORMATION AGE	
XMULTIPLE ASIA 2/F, No. 60, Jilisen St., Taipei, Taiwan 10488		XMULTIPLE USA 2854 Old Connel Road Newbury Park, CA 91380	
THIS DRAWING IS A CONTROLLED DOCUMENT.			
TITLE: RJ45 Connectors, V/LED, 8P, 8C, Shielded, Thru-Hole	REV FO0712	DRAWN VIQ	
PART NO: XRJM-S-08-8-8-X-F1	DATE 07/12/01	CHKD: C. TSAI	
DIMENSIONS Inch [mm]		SHEET 1 of 1	REV J